

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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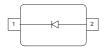
Silicon Variable Capcitance Diode

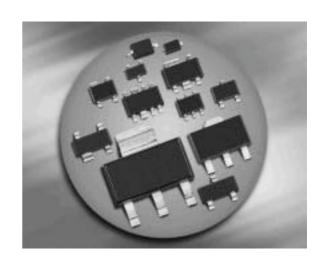
- For UHF-TV-tuners
- High capacitance ratio
- Low series inductance
- Low series resistance
- Excellent uniformity and matching due to "in-line" matching assembly procedure
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101





BB545 BB565/-02V





Туре	Package	Configuration	L S(nH)	Marking
BB545	SOD323	single	1.8	white U
BB565	SCD80	single	0.6	CC
BB565-02V	SC79	single	0.6	С

Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_{R}	30	V
Peak reverse voltage	V_{RM}	35	
$R \ge 5k\Omega$			
Forward current	l _F	20	mA
Operating temperature range	T_{op}	-55 150	°C
Storage temperature	$T_{ m stg}$	-55 150	

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¹Pb-containing package may be available upon special request



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

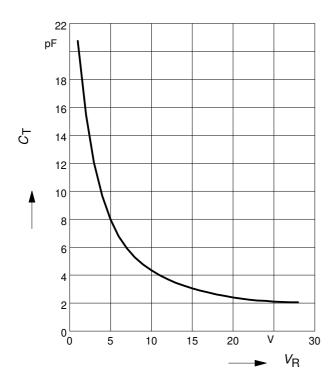
Parameter	Symbol		Unit		
		min.	typ.	max.	
DC Characteristics					
Reverse current	I _R				nA
$V_{R} = 30 \text{ V}$		-	-	10	
$V_{R} = 30 \text{ V}, T_{A} = 85 ^{\circ}\text{C}$		-	-	200	
AC Characteristics					
Diode capacitance	C_{T}				рF
$V_{R} = 1 \text{ V}, f = 1 \text{ MHz}$		18.5	20	21.5	
$V_{R} = 2 \text{ V}, f = 1 \text{ MHz}$		13.2	14.8	16.4	
$V_{R} = 25 \text{ V}, f = 1 \text{ MHz}$		1.85	2.07	2.28	
$V_{R} = 28 \text{ V}, f = 1 \text{ MHz}$		1.8	2	2.2	
Capacitance ratio	$C_{\text{T1}}/C_{\text{T28}}$	9	10	11	-
$V_{R} = 1 \text{ V}, V_{R} = 28 \text{ V}, f = 1 \text{ MHz}$					
Capacitance ratio	C_{T2}/C_{T25}	6.3	7.2	8.1	
$V_{R} = 2 \text{ V}, V_{R} = 25 \text{ V}, f = 1 \text{ MHz}$					
Capacitance matching1)	$\Delta C_{T}/C_{T}$				%
V_{R} = 1V to 28V, f = 1 MHz, 7 diodes sequence,					
BB545		-	-	2.5	
V_{R} = 1V to 28V, f = 1 MHz, 4 diodes sequence,					
BB565/-02V		-	0.5	1.5	
V_{R} = 1V to 28V, f = 1 MHz, 7 diodes sequence,					
BB565/-02V		-	0.7	2	
Series resistance	r _S	-	0.6	-	Ω
$V_{R} = 3 \text{ V}, f = 470 \text{ MHz}$					

¹For details please refer to Application Note 047



Diode capacitance $C_T = f(V_R)$

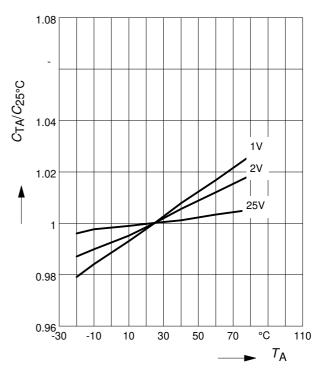
f = 1MHz



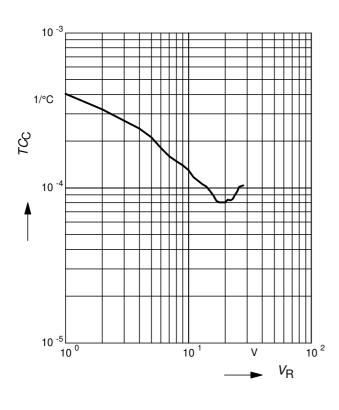
Normalized diode capacitance

 $C_{(TA)}/C_{(25^{\circ}C)} = f(T_A); f = 1MHz$

 V_{R} = Parameter

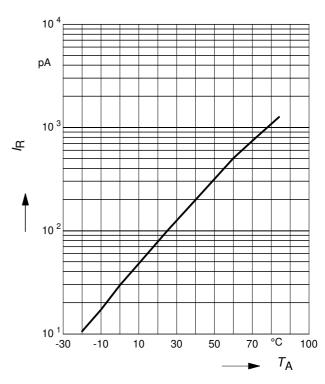


Temperature coefficient of the diode capacitance $T_{Cc} = f(V_R)$



Reverse current $I_R = f(T_A)$

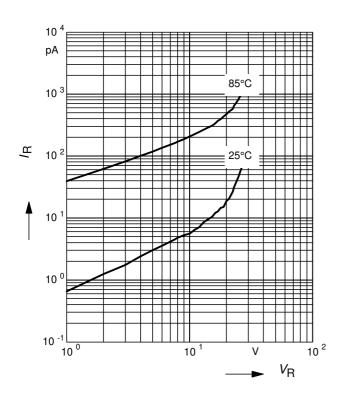
$$V_{\mathsf{R}} = 28 \mathsf{V}$$





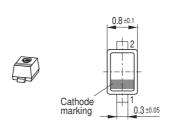
Reverse current $I_R = f(V_R)$

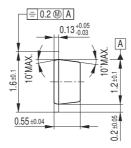
 T_A = Parameter





Package Outline

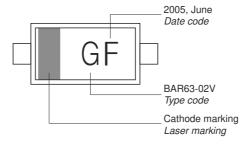




Foot Print



Marking Layout (Example)

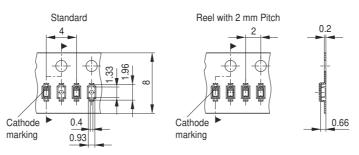


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

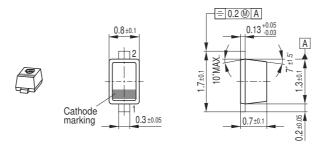
Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel





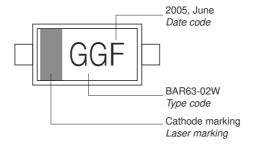
Package Outline



Foot Print



Marking Layout (Example)

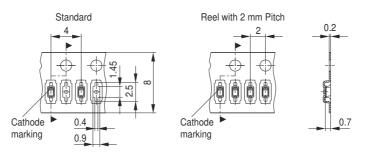


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel



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Date Code marking for discrete packages with one digit (SCD80, SC79, SC751) CES-Code

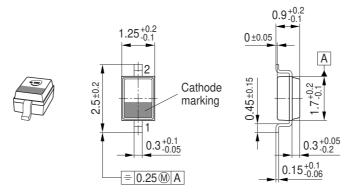
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	а	р	Α	Р	а	р	Α	Р	а	р	Α	Р
02	b	q	В	Q	b	q	В	Q	b	q	В	Q
03	С	r	С	R	С	r	С	R	С	r	С	R
04	d	S	D	S	d	S	D	S	d	S	D	S
05	е	t	Е	T	е	t	Е	Т	е	t	Е	Т
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	٧	G	٧	g	٧	G	٧	g	٧	G	V
80	h	Х	Ι	Χ	h	Х	Η	Χ	h	Х	Н	X
09	j	У	J	Υ	j	у	J	Υ	j	У	J	Υ
10	k	Z	K	Z	k	Z	K	Z	k	Z	K	Z
11	Ī	2	L	4	İ	2	L	4	İ	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

¹⁾ New Marking Layout for SC75, implemented at October 2005.

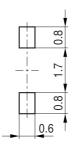
7 2007-04-20



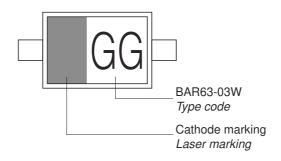
Package Outline



Foot Print

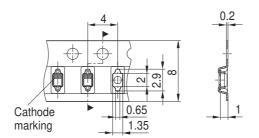


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



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2007-04-20